CT3010, CT3011, CT3012
CT3020, CT3021, CT3022, CT3023
250V/400V Random Phase 6-Pin Phototriac Optocoupler

Features

- High isolation 5000 VRMS
- Peak Breakdown Voltage
  - 250V – CT3010,3011,3012
  - 400V – CT3020,3021,3022,3023
- Temperature range - 55 ℃ to 100 ℃
- RoHS compliance
- REACH compliance
- Halogen compliance(Optional)
- Regulatory Approvals
  - UL - UL1577 (E364000)
  - VDE - EN60747-5-5(VDE0884-5)
  - CQC – GB4943.1, GB8898
  - IEC60065, IEC60950

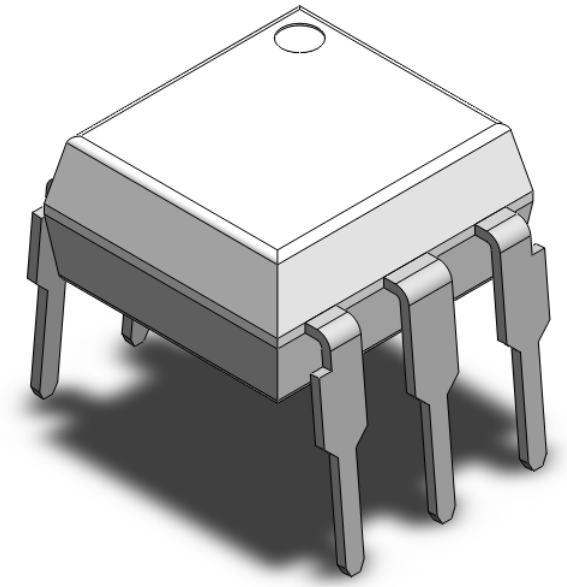
Description

The CT3010, CT3011, CT3012, CT3020, CT3021, CT3022 and CT3023 consists of a Random Phase Photo Triac optically coupled to a gallium arsenide Infrared-emitting diode in a 6-lead DIP package with different lead forming options.

Applications

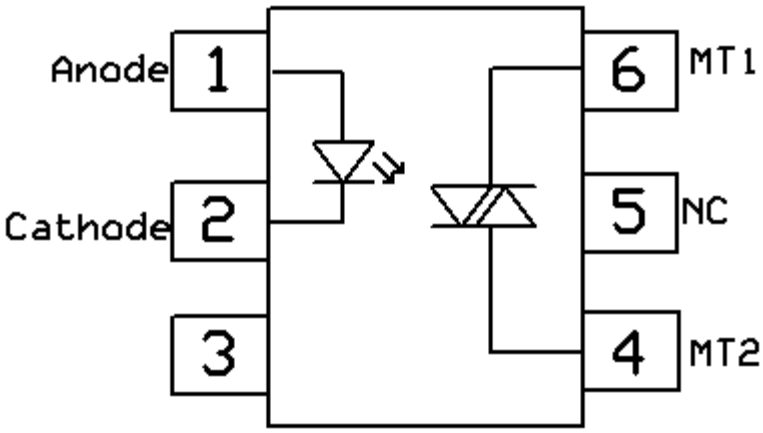
- Motor Controls
- Lamp ballasts
- Static AC Power Switch
- Solenoid/ Valve Control

Package Outline



Note: Different lead forming options available. See package dimension.

Schematic



Absolute Maximum Rating at 25°C

Symbol	*Parameters*		*Ratings*	*Units*	*Notes*
V_{ISO}	Isolation voltage		5000	V_{RMS}	
T_{OPR}	Operating temperature		-55 ~ +100	°C	
T_{STG}	Storage temperature		-55 ~ +150	°C	
T_{SOL}	Soldering temperature		260	°C	
Emitter					
I_F	Forward current		60	mA	
$I_{F(TRANS)}$	Peak transient current (≤1μs P.W,300pps)		1	A	
V_R	Reverse voltage		6	V	
P_D	Power dissipation		100	mW	
Detector					
P_D	Power dissipation		300	mW	
V_{DRM}	Off-State Output Terminal Voltage	CT3010,3011,3012	250	V	
		CT3020,3021,3022,3023	400	V	
I_{TSM}	Peak Repetitive Surge Current		1	A	

Electrical Characteristics T_A = 25℃ (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V_F	Forward voltage	I_F=10mA	-	-	1.5	V	
I_R	Reverse Current	V_R = 6V	-	-	5	μA	
C_{IN}	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I_{DRM}	Peak Blocking Current	I_F= 0mA, V_{DRM}= Rated V_{DRM}	-	-	100	nA	
V_{TM}	Peak On-State Voltage	I_F= Rated I_{FT}, I_{TM}= 100mA	-	-	2.5	V	
dv/dt	Critical Rate of Rise off-State Voltage	V_{PEAK}= Rated V_{DRM}	-	100	-	V/μs	

Transfer Characteristics

Symbol	Parameters		Test Conditions	Min	Typ	Max	Units	Notes
I_{FT}	Input Trigger Current	CT3020	Terminal Voltage = 3V I_{TM}=100mA	-	-	30	mA	
		CT3010, CT3021		-	-	15		
		CT3011, CT3022		-	-	10		
		CT3012, CT3023		-	-	5		
I_H	Holding Current			-	250	-	μA	
R_{IO}	Isolation Resistance		V_{IO}= 500V_{DC}	$1x10^{11}$	-	-	Ω	
C_{IO}	Isolation Capacitance		f= 1MHz	-	0.25	-	pF	

Typical Characteristic Curve

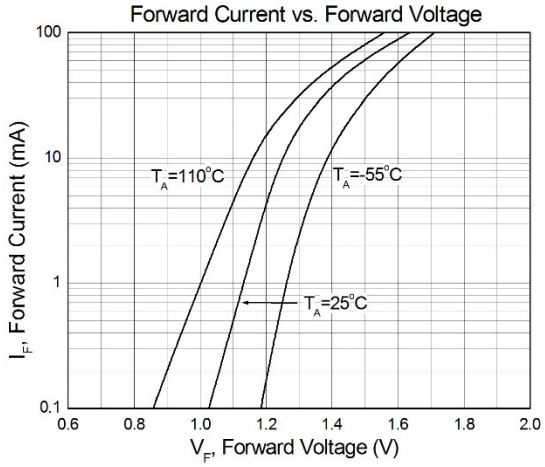


Figure 1

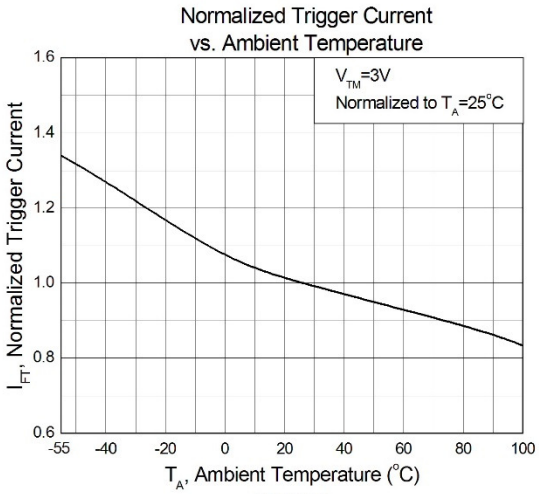


Figure 2

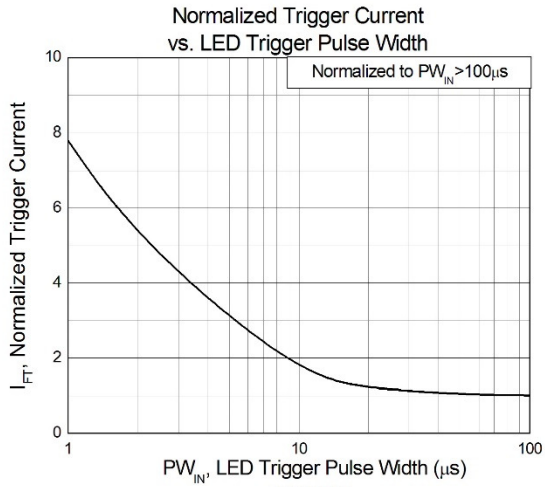


Figure 3

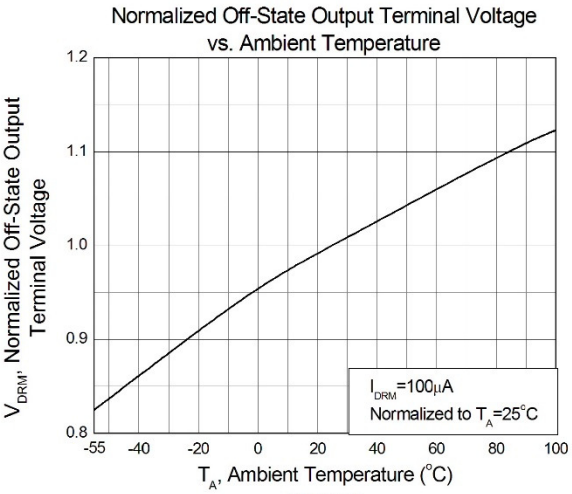


Figure 4

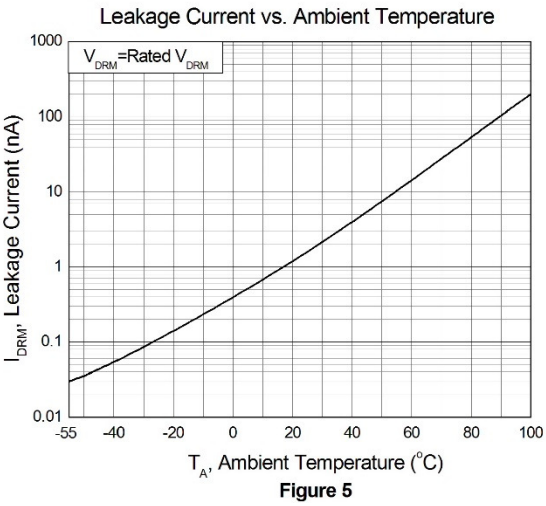


Figure 5

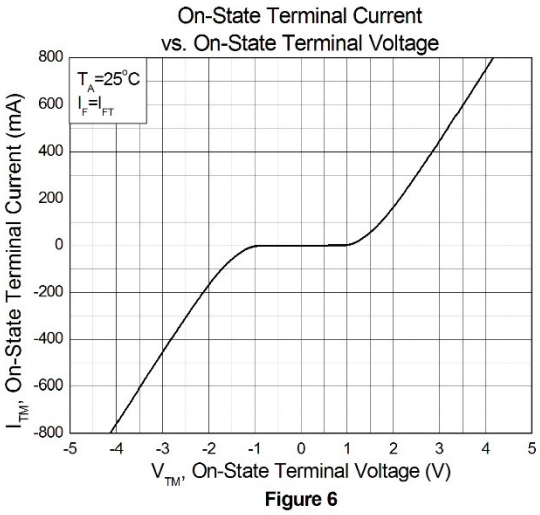


Figure 6

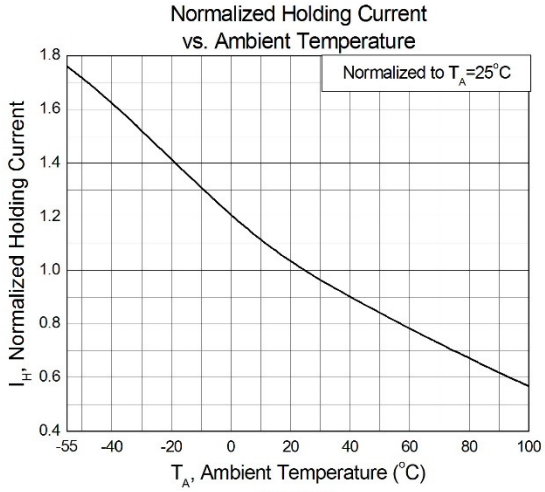
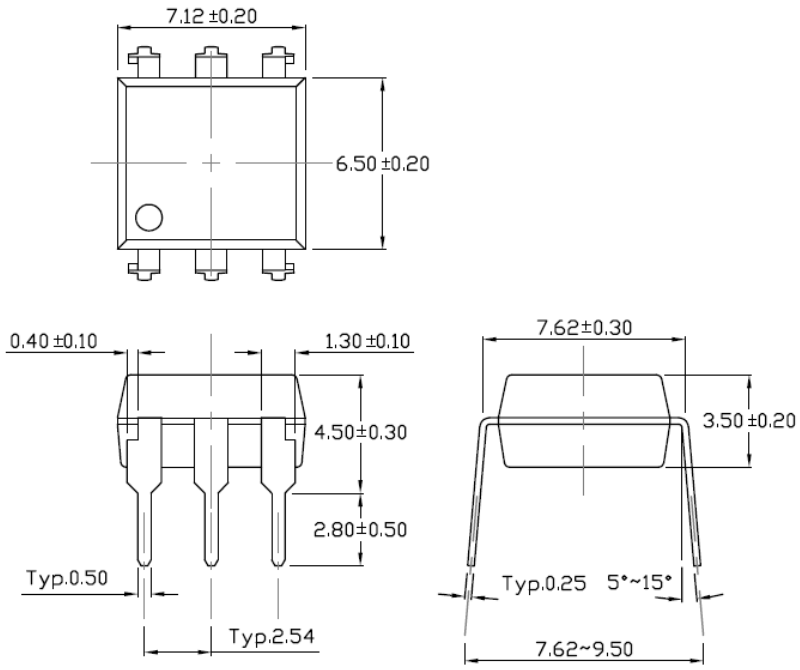

Normalized Holding Current
vs. Ambient Temperature
Normalized to T_A=25°C
I_{H^+}, Normalized Holding Current
1.8
1.6
1.4
1.2
1.0
0.8
0.6
0.4
-55
-40
-20
0
20
40
60
80
100
T_A, Ambient Temperature (°C)

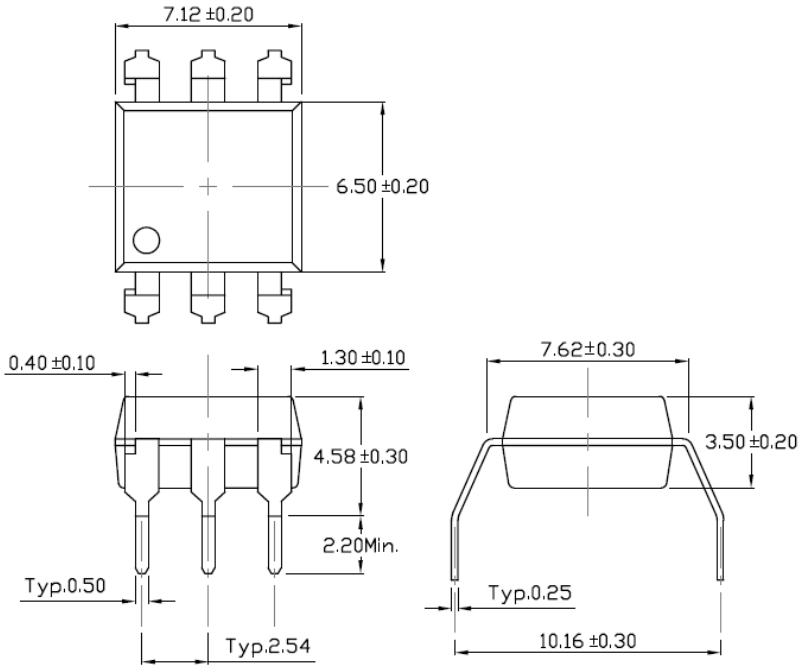
Figure 7

Package Dimension *Dimensions in mm unless otherwise stated*

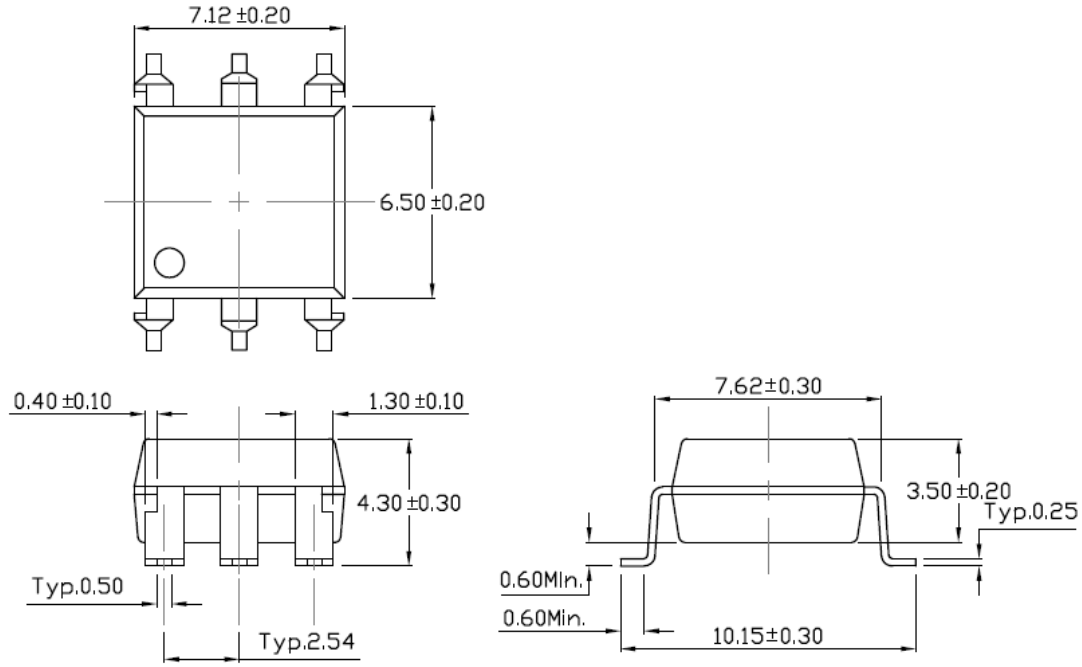
Standard DIP – Through Hole



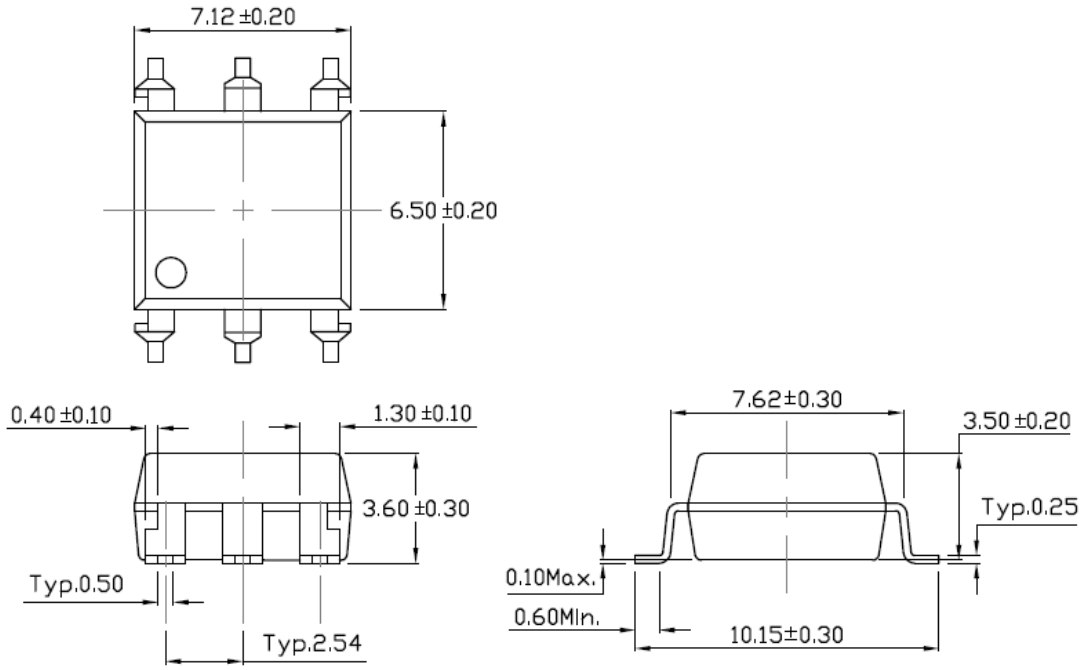
Wide Lead Forming – Through Hole (M Type)



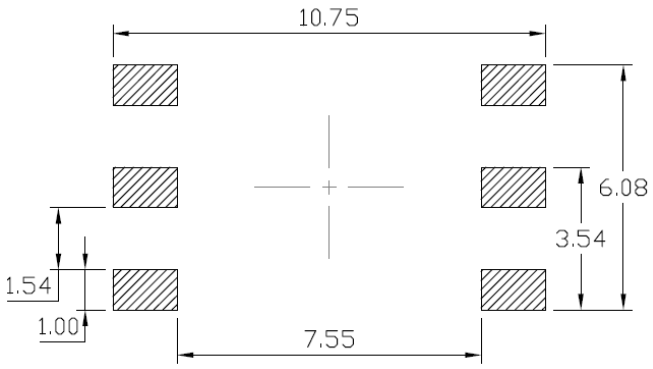
Surface Mount Forming (S Type)



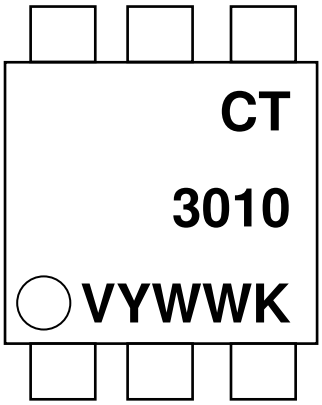
Surface Mount Forming (Low Profile) (SL Type)



Recommended Solder Mask *Dimensions in mm unless otherwise stated*



Marking Information



Note:

CT : Denotes “CT Micro”
3010 : Part Number
V : VDE Option
Y : Fiscal Year
WW : Work Week
K : Manufacturing Code

Ordering Information

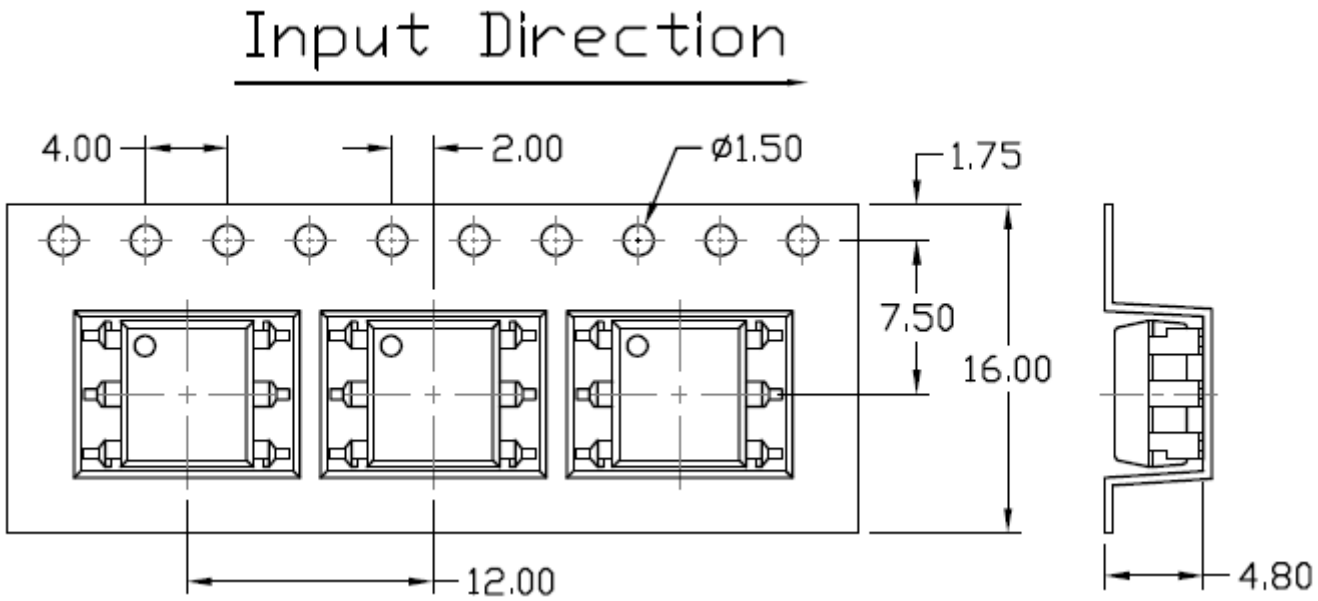
CT301X(V)(Y)(Z)-G, CT302X(V)(Y)(Z)-G

X = Part No. (CT301X:0,1,2), (CT302X : 0,1,2,3)
V = VDE Option (V or none)
Y = Lead form option (S, SL, M or none)
Z = Tape and reel option (T1, T2 or none)
G= Material option (G: Green, None: Non-green)

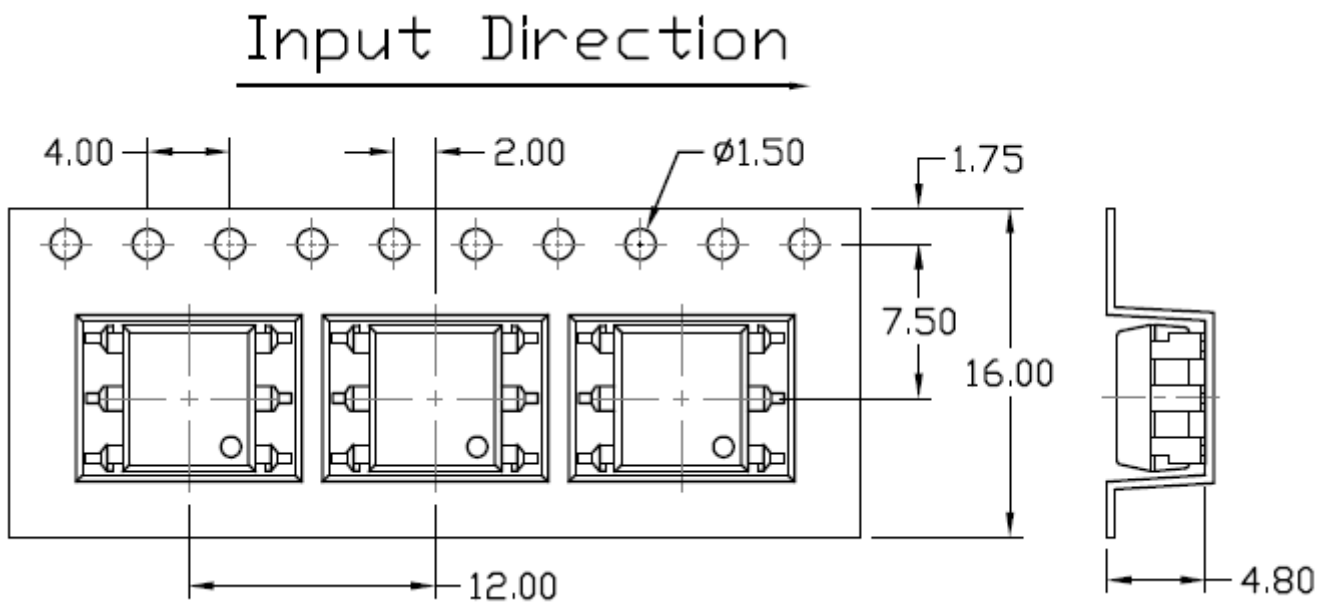
Option	***Description***	***Quantity***
None	Standard 6 Pin Dip	50Units/Tube
M	Gullwing (400mil) Lead Forming	50Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming – With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1000 Units/Reel

Carrier Tape Specifications *Dimensions in mm unless otherwise stated*

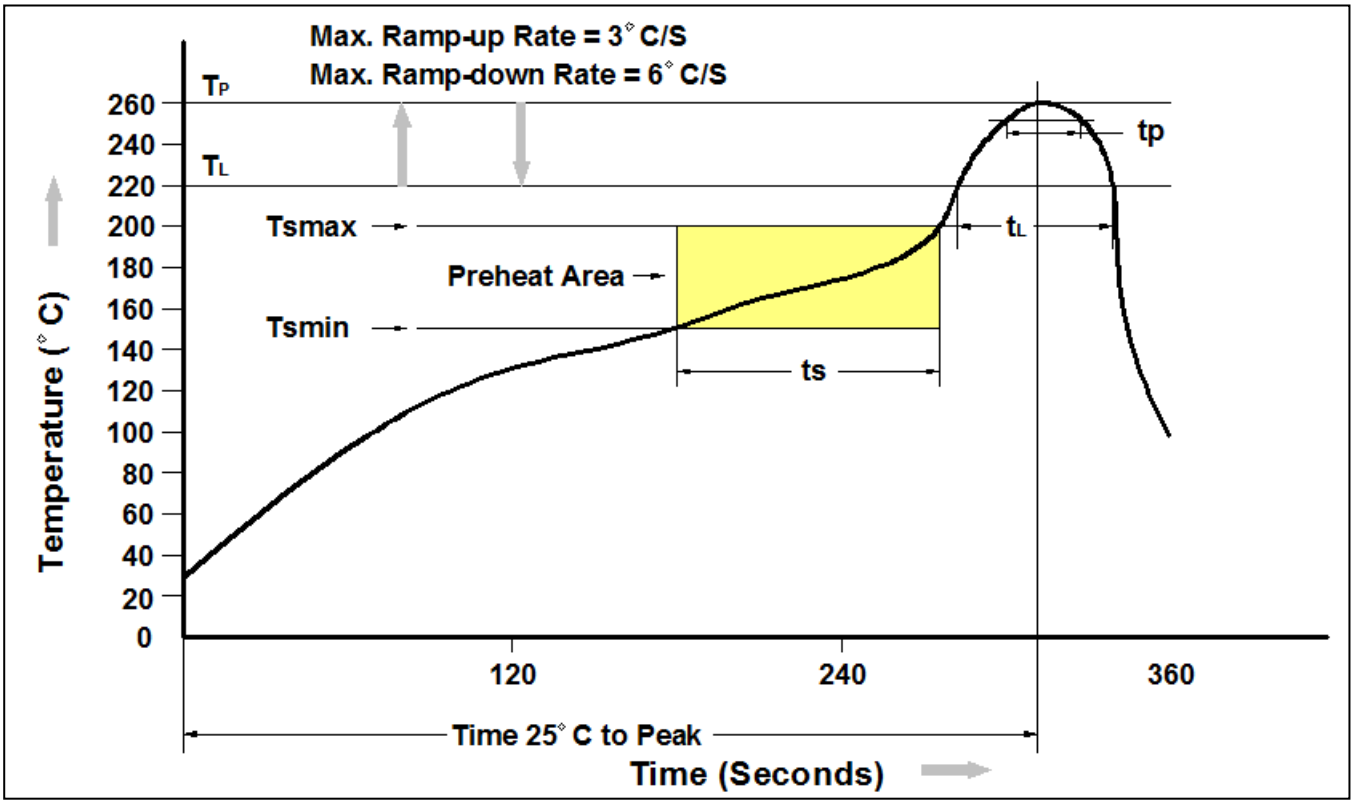
Option S(T1) & SL(T1)



Option S(T2) & SL(T2)



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150℃
Temperature Max. (Tsmax)	200℃
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t_L to t_P)	3℃/second max.
Liquidous Temperature (T_L)	217℃
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Body Package Temperature	260℃ +0℃ / -5℃
Time (t_P) within 5℃ of 260℃	30 seconds
Ramp-down Rate (T_P to T_L)	6℃/second max
Time 25℃ to Peak Temperature	8 minutes max.

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